

Product Change Notification / SYST-30GU0E517

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10-Jul-2023

Product Category:

8-bit Microcontrollers

PCN Type:

Document Change

Notification Subject:

ERRATA - PIC18F04/05/14/15Q41 Silicon Errata and Data Sheet Clarifications

Affected CPNs:

SYST-30GUOE517_Affected_CPN_07102023.pdf SYST-30GUOE517_Affected_CPN_07102023.csv

Notification Text:

SYST-30GUOE517

Microchip has released a new Errata for the PIC18F04/05/14/15Q41 Silicon Errata and Data Sheet Clarifications of devices. If you are using one of these devices please read the document located at PIC18F04/05/14/15Q41 Silicon Errata and Data Sheet Clarifications.

Notification Status: Final

Description of Change: Adding silicon revision E0. Adding silicon errata 1.4.3, 1.4.4, 1.4.5 and 1.9.1.

Impacts to Data Sheet: None

Reason for Change: To Improve Productivity

Change Implementation Status: Complete

Date Document Changes Effective: 10 Jul 2023

NOTE: Please be advised that this is a change to the document only the product has not been changed.

Markings to Distinguish Revised from Unrevised Devices: N/A

Attachme	ents:
PIC18F04/0	05/14/15Q41 Silicon Errata and Data Sheet Clarifications
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Affected Catalog Part Numbers (CPN)

PIC18F04Q41-E/SL

PIC18F04Q41-E/ST

PIC18F04Q41-I/SL

PIC18F04Q41-I/ST

PIC18F04Q41/SD02

PIC18F04Q41T-I/SL

PIC18F04Q41T-I/ST

PIC18F05Q41-E/SL

PIC18F05Q41-E/ST

PIC18F05Q41-I/SL

PIC18F05Q41-I/ST

PIC18F05Q41T-I/SL

PIC18F05Q41T-I/ST

PIC18F14Q41-E/P

PIC18F14Q41-E/REB

PIC18F14Q41-E/SO

PIC18F14Q41-E/SS

PIC18F14Q41-I/P

PIC18F14Q41-I/REB

PIC18F14Q41-I/SO

PIC18F14Q41-I/SS

PIC18F14Q41T-I/REB

PIC18F14Q41T-I/SO

PIC18F14Q41T-I/SS

PIC18F15Q41-E/P

PIC18F15Q41-E/REB

PIC18F15Q41-E/SO

PIC18F15Q41-E/SS

PIC18F15Q41-I/P

PIC18F15Q41-I/REB

PIC18F15Q41-I/SO

PIC18F15Q41-I/SS

PIC18F15Q41T-I/REB

PIC18F15Q41T-I/SO

PIC18F15Q41T-I/SS

PIC18F04/05/14/15Q41 Silicon Errata and Data Sheet Clarifications



PIC18F04/05/14/15Q41

The PIC18F04/05/14/15Q41 devices that you have received conform functionally to the current device data sheet (DS40002242**D**), except for the anomalies described in this document.

The silicon issues discussed in the following pages are for silicon revisions with the Device and Revision IDs listed in the table below.

The errata described in this document will be addressed in future revisions of the PIC18F04/05/14/15Q41 silicon.

Note: This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current.

Table 1. Silicon Device Identification

Part Number	Device ID	Revision ID				
rait Nullibel	Device ID	A4	A5	D1	D3	E0
PIC18F04Q41	0x7540	0xA004	0xA005	0xA0C1	0xA0C3	0xA0D0
PIC18F05Q41	0x7500	0xA004	0xA005	0xA0C1	0xA0C3	0xA0D0
PIC18F14Q41	0x7520	0xA004	0xA005	0xA0C1	0xA0C3	0xA0D0
PIC18F15Q41	0x75E0	0xA004	0xA005	0xA0C1	0xA0C3	0xA0D0



Important: Refer to the **Device/Revision ID** section in the current "**PIC18-Q41 Family Programming Specification**" (DS40002143) for more detailed information on Device Identification and Revision IDs for your specific device.

Table 2. Silicon Issue Summary

NA - de la	Facture	Feature Item No.	lanca Comanana	Affected Revisions				
Module	reature	item No.	lssue Summary	A4	A5	D1	D3	E0
Analog-to-Digital	ADCC	1.1.1	ADC cannot operate in certain low-power conditions	Χ				
Converter with Computation		1.1.2	Double Sample Conversions	Χ	Х	Х	Χ	
Electrical Specifications	ADC Offset Error	1.2.1	ADC Offset Error specification lowered in ECH, ECM and ECL modes			X		
	XT mode	1.3.1	Maximum clock frequency limited to 2 MHz for XT mode	Χ				
Oscillator	Fail-Safe Clock Monitor	1.3.2	Enabling the FOSC Fail-Safe Clock Monitor alongside the Primary or Secondary Oscillator Clock Monitor causes issues in Sleep	Х				
	EC mode	1.3.3	Maximum clock frequency for EC mode is 32 MHz for $V_{\rm DD}$ < 2.0V	Χ				
I ² C	I ² C	1.4.1	I2CxADR0/1/2/3 registers have incorrect Reset value	Χ				
		1.4.2	I ² C Start and/or Stop Flags may be set when I ² C is enabled	Χ	Х	X		
		1.4.3	MDR bit is not cleared after Bus Timeout	Х	Х	Х	Χ	
		1.4.4	Bus Timeout not detected properly when External Host Clock stretches	Χ	Χ	Х	Х	
		1.4.5	Clock Stretch Disable not working properly	Χ	Х	Х	Χ	
		1.4.6	Bus Timeout causes false Start/Stop	Χ	Х	Х	Χ	
Operational	OPA	1.5.1	The Charge Pump On Control (CPON) bit is reserved	Χ				
Amplifier	OPA	1.5.2	Internal resistor ladder does not disconnect in Unity Gain mode	Χ				
Universal Asynchronous	UART	1.6.1	UART TXDE signal may go low before the STOP bit has been entirely transmitted.	Χ	Х	Х	Х	
Receiver Transmitter		1.6.2	Asynchronous 9-bit UART Address mode address mismatch	Χ	Χ	X	Х	
Signal Measurement Timer	SMT	1.7.1	Reset Bit	Х	Х	Х	X	
PIC18 CPU	FSR Shadow Registers	1.8.1	FSR Shadow Registers are not writable	Χ	Х	Х	Х	
ICSP	Low-Voltage Programming (LVP)	1.9.1	Low Voltage Programming is not possible when VDD is below BORV while BOR is enabled.	Х	Х	Х		

Note: Only those issues indicated in the last column apply to the current silicon revision.



1. Silicon Errata Issues



Notice: This document summarizes all silicon errata issues from all revisions of silicon, previous and current. Only the issues indicated by the bold font in the following tables apply to the current silicon revision.

1.1 Module: Analog-to-Digital Converter with Computation (ADCC)

1.1.1 ADC Cannot Operate in Certain Low-Power Conditions

The ADC will not function when all of the following conditions exist: When the MCU system clock is sourced from LFINTOSC or SOSC and when both the BOR and FVR features are disabled.

Work around

- Method 1: Use a system clock other than LFINTOSC or SOSC.
- Method 2: Enable the BOR feature.
- Method 3: Enable the FVR feature.

Affected Silicon Revisions

A4	A5	D1	D3	EO
X				

1.1.2 Double Sample Conversions

When enabling a Double Sample Conversion (DSEN = 1) with no Precharge time (ADPRE = 0) and no Acquisition time (ADACQ = 0), the maximum number of cycles of acquisition time is inserted prior to the second conversion. The first conversion will be performed as expected with no Precharge time and no Acquisition time. It is only between the first and second conversions where a maximum number of cycles of Acquisition time is performed unexpectedly.

Work around

Method 1:

Disable Double Sample Conversion (DSEN = 0) and perform two single conversions back to back.

Method 2:

If adding acquisition time is acceptable, then select no Precharge time, along with the desired Acquisition time.

Affected Silicon Revisions

A4	A5	D1	D3	EO
X	X	X	X	

1.2 Module: Electrical Specifications

1.2.1 ADC Offset Error Specification Lowered in ECH, ECM and ECL Modes

When operating the device using an external clock source as the system clock in ECH, ECM or ECL mode, the ADC Offset Error (AD04: E_{OFF}) is updated to 12 Least Significant bits.

Work around

To meet the specified ADC Offset Error limit of 6 Least Significant bits, do not operate the device using the system clock in ECH, ECM or ECL mode when using the ADC.



Affected Silicon Revisions

A4	A5	D1	D3	EO
		X		

1.3 Module: Oscillator (OSC)

1.3.1 Maximum Clock Frequency Limited to 2 MHz for XT Mode

The maximum clock frequency for the intermediate gain setting that supports quartz crystal and ceramic resonator operation (XT mode) is being reduced from 4 MHz to 2 MHz.

Work around

For crystal or resonator frequencies above 2 MHz, use HS mode.

Affected Silicon Revisions

A4	A5	D1	D3	EO
X				

1.3.2 Enabling the FOSC Fail-Safe Clock Monitor Alongside the Primary or Secondary Oscillator Clock Monitor Causes Issues with Sleep

When the FOSC Fail-Safe Clock Monitor is enabled (FCMEN Configuration bit = 1) and either the Primary or Secondary Fail-Safe Clock Monitor is also enabled (FCMENS and/or FCMENP = 1), putting the device to Sleep will cause a Fail-Safe condition to trigger. This has the effect of erroneously triggering Fail-Safe interrupts when there has not been a clock interruption. This can also cause the Watchdog Timer to not properly wake up the part from Sleep.

Work around

If proper functionality in Sleep is required, do not enable the Primary or Secondary Fail-Safe Clock Monitor while the FOSC Fail-Safe Clock Monitor is enabled. If Primary or Secondary Clock Monitoring in Sleep is desired, disable the FOSC Fail-Safe Clock Monitor before the device goes to Sleep.

Affected Silicon Revisions

A4	A5	D1	D3	EO
X				

1.3.3 Maximum Clock Frequency for EC Mode Is 32 MHz for V_{DD} < 2.0V

When configured in External Clock High-Power (ECH) mode and operating at V_{DD} < 2.0V, the maximum input clock frequency is 32 MHz.

Work around

To obtain a system clock frequency of 64 MHz in ECH mode at V_{DD} < 2.0V, use a 16 MHz external clock in conjunction with the 4x Phase-Locked Loop (PLL) circuit (i.e., either RSTOSC Configuration bits = 0b010 or OSCCON1bits.NOSC = 0b010).

Affected Silicon Revisions

A4	A5	D1	D3	EO
X				

1.4 Module: Inter-Integrated Circuit (I²C)

1.4.1 The I2CxADR0/1/2/3 Registers Have Incorrect Reset Value

The I2CxADR0/2 registers reset to $0 \times FF$ when the I2CxMD is enabled instead of 0×00 . The I2CxADR1/3 registers reset to $0 \times FE$ when the I2CxMD is enabled instead of 0×00 .



Work around

None.

Affected Silicon Revisions

A4	A5	D1	D3	EO
X				

1.4.2 The I²C Start and/or Stop Flags May Be Set When I²C Is Enabled

When I^2C is enabled, erroneous Start and/or Stop conditions may be detected. This can generate erroneous I^2C interrupts if enabled.

Work around

Use the following procedure to correctly detect the Start and Stop conditions:

- 1. Disable the Start and Stop conditions interrupt functions.
- 2. Enable the I²C module.
- 3. Wait 250 ns + six instructions cycles ($F_{OSC}/4$).
- 4. Clear the Start and Stop conditions interrupt flags.
- 5. Enable the Start and Stop conditions interrupt functions if used.

```
I2CxPIEbits.SCIE = 0:
                             // Disable Start condition interrupt
I2CxPIEbits.PCIE = 0;
                             // Disable Stop condition interrupt
I2CxCON0bits.EN = 1;
                             // Enable I2C
Delay();
                             // Wait for 250 ns + 6 instruction cycles (Fosc/4)
                             // Clear the Start condition interrupt flags
I2CxPIRbits.SCIF = 0;
I2CxPIRbits.PCIF = 0;
                             // Clear the Stop condition interrupt flags
I2CxPIEbits.SCIE = 1;
                             // Enable Start condition interrupt if used
I2CxPIEbits.PCIE = 1;
                             // Enable Stop condition interrupt if used
```

Affected Silicon Revisions

A4	A5	D1	D3	EO
X	X	X		

1.4.3 MDR Bit Is Not Cleared after Bus Timeout

In the Host mode of the I^2C module, when a bus timeout occurs during clock stretching and TOREC = 1, the MDR bit will not be cleared and a Stop will not be transmitted on the bus.

Work around

Force a Stop on the bus by setting the P bit upon bus timeout in Host mode. Forcing a Stop on the bus clears the MDR bit.

Affected Silicon Revisions

A4	A5	D1	D3	EO
X	Х	X	X	X

1.4.4 Bus Timeout Not Detected Properly when External Host Clock Stretches

When the module is operating in Client mode and an external Host device is clock stretching after the eighth SCL clock and a bus timeout occurs, the bus timeout is not detected properly. When the external Host times out before the Client and releases SCL to generate a Stop condition, the module continues to stretch SDA as if to generate an ACK and hangs the bus, and a Stop is never seen on the bus.

Work around

Reset the module by toggling the EN bit.



Affected Silicon Revisions

A4	A5	D1	D3	EO
X	Х	X	X	X

1.4.5 Clock Stretch Disable Not Working Properly

When the CSD bit is set between a Start condition and the eighth falling SCL edge, the I²C module enters a state where the module clock stretches indefinitely after the next Start until a bus timeout occurs.

Work around

Force a reset of the module by toggling the EN bit.

Affected Silicon Revisions

A4	A5	D1	D3	EO
X	X	X	X	X

1.4.6 Clock Stretch Disable Not Working Properly

When the module is operating in Client mode and an external Host device is clock stretching and a bus timeout occurs in the Client, the Client releases SDA and goes into the idle state. After the external Host generates a Stop condition on the bus by releasing SCL, the module can erroneously drive a low pulse on the SDA line, which acts as a false Start and Stop on the bus.

Work around

None.

Affected Silicon Revisions

A4	A5	D1	D3	EO
X	X	X	X	X

1.5 Module: Operational Amplifier

1.5.1 The Charge Pump On Control (CPON) Bit Is Reserved

When not operating the OPA near the rails, the Charge Pump On Control (CPON) bit can be used to disable the charge pump in order to save on current consumption. This feature is currently not available, and the charge pump is always enabled whenever the OPA module is in operation.

Work around

None.

Affected Silicon Revisions

A4	A5	D1	D3	EO
X				

1.5.2 Internal Resistor Ladder Does Not Disconnect in Unity Gain Mode

When using the OPA module in a unity gain configuration, the internal resistor ladder will not automatically disconnect from the operational amplifier, which may adversely affect the gain of the circuit. This applies when the peripheral has been configured to operate in Unity Gain mode in software by setting the UG bit, or in hardware using the hardware controlled override feature.

Work around

Disconnect the internal resistor ladder from the operational amplifier by writing to the Inverting Input Channel Selection (NCH) bits. All signals can be disconnected from the operational amplifier by writing <code>0b000</code> to the NCH bits.



Affected Silicon Revisions

A4	A5	D1	D3	E0
X				

1.6 Module: Universal Asynchronous Receiver Transmitter (UART)

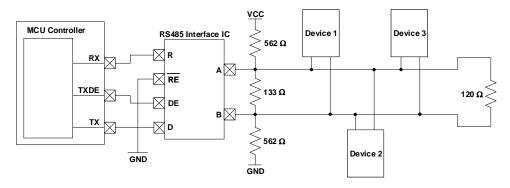
1.6.1 UART TXDE Signal May Go Low Before the STOP Bit Has Been Entirely Transmitted

The UART Transmit Drive Enable (TXDE) signal could potentially transition into a low state before the UART STOP bit has been entirely transmitted due to the effects of parasitic capacitance on the TX line. In some applications, this could result in communication being prematurely terminated due to the TXDE bit going low before the STOP bit has had enough time to settle.

Work around

To ensure that the STOP bit settles into its final logic state before the TXDE signal transitions low, a biasing circuit can be implemented. A biasing circuit allows the TX line to either be driven high or low, rather than being left in a floating tri-state mode where prolonged rise or fall times could lead to communication being disrupted. This bias circuit should only be implemented on one end of the serial bus, and a termination resistor should be used on the other end. The figure below show an example of a bias circuit that can be used to achieve this.

Please note that the resistor values used in this circuit are recommendations, and that the actual resistor values required may vary based on the application.



Affected Silicon Revisions

A4	A5	D1	D3	E0
X	X	X	X	

1.6.2 Asynchronous 9-bit UART Address Mode Address Mismatch

In Asynchronous 9-bit UART Address mode there is the possibility that a false address mismatch may occur even when the address of both devices match, or that a false address match may occur when there is an address mismatch between the devices.

Work around

None. Do not use the UART modules in Asynchronous 9-bit Address Mode

Affected Silicon Revisions

A4	A5	D1	D3	EO
X	X	X	X	X



1.7 Module: Signal Measurement Timer (SMT)

1.7.1 Reset Bit

If the SMT clock prescaler is set to any value other than '00', setting the RST bit will cause the module to stop working. The RST bit will remain at the value '1', the counter will not increment, and no interrupts will be generated. The problem is cleared by turning the module off and on, or by a device reset.

Work around

Method 1:

Do not set the RST bit; manual reset is usually not required for typical operation because the measurement logic will reset the counter automatically.

Method 2:

Write zero to the counter manually. The module enable or the clock should be disabled when using this method.

Method 3:

Use 1:1 prescaler (PS = 00).

Method 4:

Use the CLKREF subsystem to provide a prescaled clock and set PS = 00.

Affected Silicon Revisions

A4	A5	D1	D3	EO
X	X	X	X	

1.8 Module: PIC18 Core

1.8.1 FSR Shadow Registers Are Not Writable

Writing to the FSR Shadow Registers does not result in accurate values being stored in the registers. Consequently, reading the FSR Shadow Registers after they have been written will return inaccurate data.

Work around

Writes to the FSR shadow registers can be performed safely using the following steps:

- 1. Save regular FSR2 value into RAM.
- 2. Write the regular FSR2 with the targeted value minus the computed offset (IR[6:0] + 1, see below).
- 3. Write the shadow FSRxL (data doesn't matter), this will clock the shadow FSR with the FSR computed offset value.
- 4. Decrement FSR2 value by 1 since FSRxH increments the address by 1 (IR[6:0]).
- 5. Write FSRxH.
- 6. Restore the regular FSR2 from the stored RAM value.

The FSR shadow should have the value desired and the regular FSR should have the original value.

Affected Silicon Revisions

A4	A5	D1	D3	EO
X	X	X	X	



1.9 Module: Low-Voltage In-Circuit Serial Programming[™] (LVP)

1.9.1 Low-Voltage Programming Not Possible

Low-Voltage Programming is not possible when V_{DD} is below the selected BORV voltage level while BOR is enabled.

Work around

Method 1:

Disable BOR to use Low-Voltage Programming.

Method 2:

Raise V_{DD} above the selected BORV level while using Low-Voltage Programming.

Affected Silicon Revisions

A4	A5	D1	D3	EO
X	X	X		



2. Data Sheet Clarifications

The following typographic corrections and clarifications are to be noted for the latest version of the device data sheet (DS40002242**D**):

Note:

Corrections are shown in **bold**. Where possible, the original bold text formatting has been removed for clarity.

2.1 None

There are no known data sheet clarifications as of this publication date.



Appendix A: Revision History 3.

Doc. Rev.	Date	Comments
G	06/2023	Adding silicon revision E0. Adding silicon errata 1.4.3, 1.4.4, 1.4.5 and 1.9.1.
F	05/2022	Adding silicon revision D3.
E	04/2022	Updating the flash memory cell endurance specification data sheet clarification. Adding silicon errata 1.8.1
D	02/2022	Adding silicon errata 1.1.2, 1.6.1 and 1.7.1.
С	02/2021	Adding ADC offset errata and updating mask revision for KV00P RTP. Adding silicon revision D1. Adding silicon errata 1.5 and 1.6. Minor editorial corrections.
В	11/2020	Adding silicon revision A5.
Α	07/2020	Initial document release.



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